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Thermal conductivity and electrical resistivity dependences on growth rate in the directionally solidified Al–Cu–Ni eutectic alloy

Ümit Bayram, Necmettin Maraşli

PII: S0925-8388(18)31600-1

DOI: 10.1016/j.jallcom.2018.04.277

Reference: JALCOM 45915

To appear in: *Journal of Alloys and Compounds*

Received Date: 15 March 2018

Revised Date: 23 April 2018

Accepted Date: 24 April 2018

Please cite this article as: Ü. Bayram, N. Maraşli, Thermal conductivity and electrical resistivity dependences on growth rate in the directionally solidified Al–Cu–Ni eutectic alloy, *Journal of Alloys and Compounds* (2018), doi: 10.1016/j.jallcom.2018.04.277.

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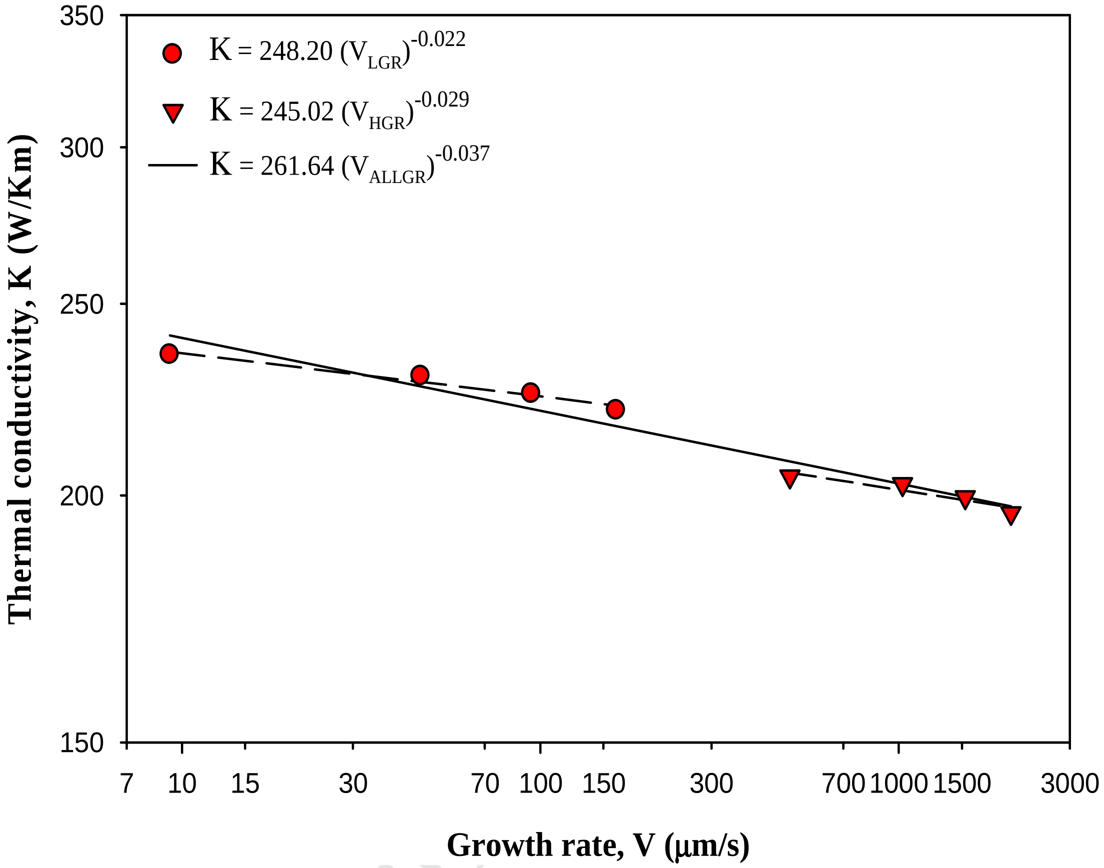
Graphical Abstract



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